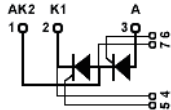
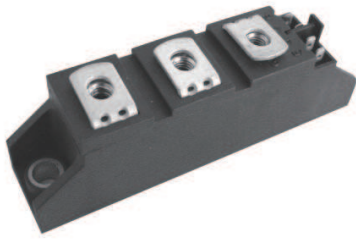


# STT27GKxx

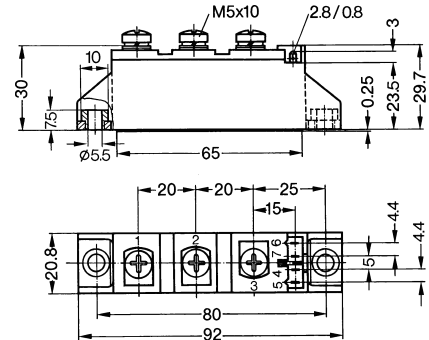
## Thyristor-Thyristor Modules



Type	$V_{RSM}$ $V_{DSM}$ V	$V_{RRM}$ $V_{DRM}$ V
STT27GK08	900	800
STT27GK12	1300	1200
STT27GK14	1500	1400
STT27GK16	1700	1600

Tolerance:  $\pm 0.5\text{mm}$

Dimensions in mm (1mm=0.0394")



Symbol	Test Conditions	Maximum Ratings	Unit
$I_{TRMS}, I_{FRMS}$ $I_{TAVM}, I_{FAVM}$	$T_{VJ}=T_{VJM}$ $T_C=85^\circ\text{C}; 180^\circ$ sine	50 27	A
$I_{TSM}, I_{FSM}$	$T_{VJ}=45^\circ\text{C}$ $V_R=0$ $t=10\text{ms}$ (50Hz), sine $t=8.3\text{ms}$ (60Hz), sine	520 560	A
	$T_{VJ}=T_{VJM}$ $V_R=0$ $t=10\text{ms}$ (50Hz), sine $t=8.3\text{ms}$ (60Hz), sine	460 500	
$\int i^2 dt$	$T_{VJ}=45^\circ\text{C}$ $V_R=0$ $t=10\text{ms}$ (50Hz), sine $t=8.3\text{ms}$ (60Hz), sine	1350 1300	$\text{A}^2\text{s}$
	$T_{VJ}=T_{VJM}$ $V_R=0$ $t=10\text{ms}$ (50Hz), sine $t=8.3\text{ms}$ (60Hz), sine	1050 1030	
$(di/dt)_{cr}$	$T_{VJ}=T_{VJM}$ $f=50\text{Hz}, t_p=200\mu\text{s}$ $V_D=2/3V_{DRM}$ $I_G=0.45\text{A}$ $di_G/dt=0.45\text{A}/\mu\text{s}$	repetitive, $I_T=45\text{A}$ 150	A/ $\mu\text{s}$
		non repetitive, $I_T=I_{TAVM}$ 500	
$(dv/dt)_{cr}$	$T_{VJ}=T_{VJM};$ $R_{GK}=\infty;$ method 1 (linear voltage rise)	$V_{DR}=2/3V_{DRM}$ 1000	V/ $\mu\text{s}$
$P_{GM}$	$T_{VJ}=T_{VJM}$ $I_T=I_{TAVM}$	$t_p=30\mu\text{s}$ 10	W
		$t_p=300\mu\text{s}$ 5	
$P_{GAV}$		0.5	W
$V_{RGM}$		10	V
$T_{VJ}$ $T_{VJM}$ $T_{stg}$		-40...+125	$^\circ\text{C}$
		125	
		-40...+125	
$V_{ISOL}$	50/60Hz, RMS $I_{ISOL} \leq 1\text{mA}$	$t=1\text{min}$ 3000	V~
		$t=1\text{s}$ 3600	
$M_d$	Mounting torque (M5) Terminal connection torque (M5)	2.5-4.0/22-35	Nm/lb.in.
		2.5-4.0/22-35	
Weight	Typ.	81	g

# STT27GKxx

## Thyristor-Thyristor Modules

Symbol	Test Conditions	Characteristic Values	Unit
$I_{RRM}, I_{DRM}$	$T_{VJ}=T_{VJM}; V_R=V_{RRM}; V_D=V_{DRM}$	3	mA
$V_T, V_F$	$I_T, I_F=80A; T_{VJ}=25^{\circ}C$	1.64	V
$V_{TO}$	For power-loss calculations only ( $T_{VJ}=125^{\circ}C$ )	0.85	V
$r_T$		11	m $\Omega$
$V_{GT}$	$V_D=6V; T_{VJ}=25^{\circ}C$	1.5	V
	$T_{VJ}=-40^{\circ}C$	1.6	
$I_{GT}$	$V_D=6V; T_{VJ}=25^{\circ}C$	100	mA
	$T_{VJ}=-40^{\circ}C$	200	
$V_{GD}$	$T_{VJ}=T_{VJM}; V_D=2/3V_{DRM}$	0.2	V
$I_{GD}$		10	mA
$I_L$	$T_{VJ}=25^{\circ}C; t_p=10\mu s; V_D=6V$ $I_G=0.45A; di_G/dt=0.45A/\mu s$	450	mA
$I_H$	$T_{VJ}=25^{\circ}C; V_D=6V; R_{GK}=\infty$	200	mA
$t_{gd}$	$T_{VJ}=25^{\circ}C; V_D=1/2V_{DRM}$ $I_G=0.45A; di_G/dt=0.45A/\mu s$	2	$\mu s$
$t_q$	$T_{VJ}=T_{VJM}; I_T=20A; t_p=200\mu s; -di/dt=10A/\mu s$ $V_R=100V; dv/dt=20V/\mu s; V_D=2/3V_{DRM}$	typ. 150	$\mu s$
$Q_s$	$T_{VJ}=T_{VJM}; I_T, I_F=25A; -di/dt=0.64A/\mu s$	50	$\mu C$
$I_{RM}$		6	A
$R_{thJC}$	per thyristor/diode; DC current per module	0.88	K/W
		0.44	
$R_{thJK}$	per thyristor/diode; DC current per module	1.08	K/W
		0.54	
$d_s$	Creeping distance on surface	12.7	mm
$d_A$	Strike distance through air	9.6	mm
$a$	Maximum allowable acceleration	50	m/s <sup>2</sup>

### FEATURES

- \* International standard package
- \* DCB base plate
- \* Glass passivated chips
- \* Isolation voltage 3600 V~
- \* UL file NO.310749
- \* RoHs compliant

### APPLICATIONS

- \* DC motor control
- \* Softstart AC motor controller
- \* Light, heat and temperature control

### ADVANTAGES

- \* Space and weight savings
- \* Simple mounting with two screws
- \* Improved temperature and power cycling
- \* Reduced protection circuits

# STT27GKxx

## Thyristor-Thyristor Modules

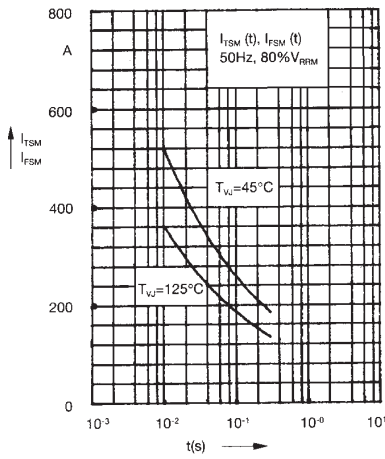


Fig. 1 Surge overload current  
 $I_{TSM}$ ,  $I_{FSM}$ : Crest value, t: duration

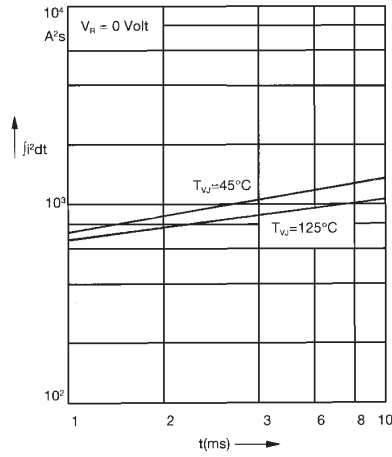


Fig. 2  $j^2dt$  versus time (1-10 ms)

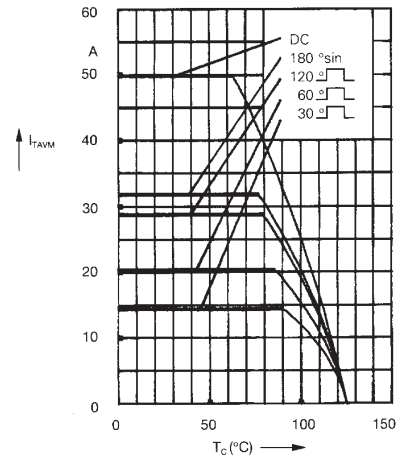


Fig. 2a Maximum forward current at case temperature

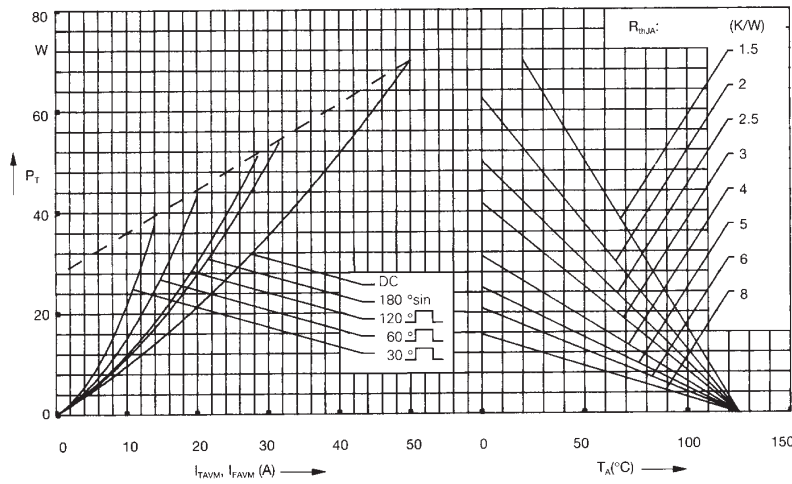


Fig. 3 Power dissipation versus on-state current and ambient temperature (per thyristor or diode)

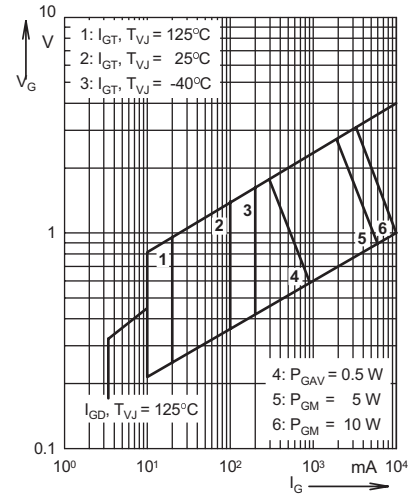


Fig. 4 Gate trigger characteristics

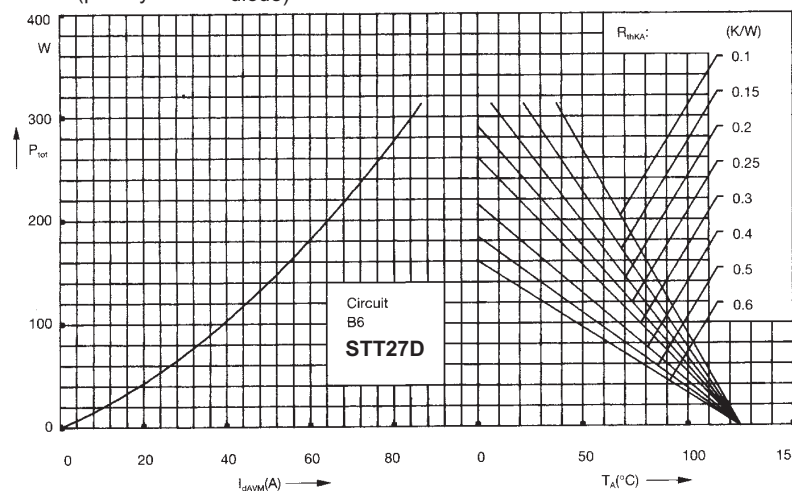


Fig. 5 Three phase rectifier bridge: Power dissipation versus direct output current and ambient temperature

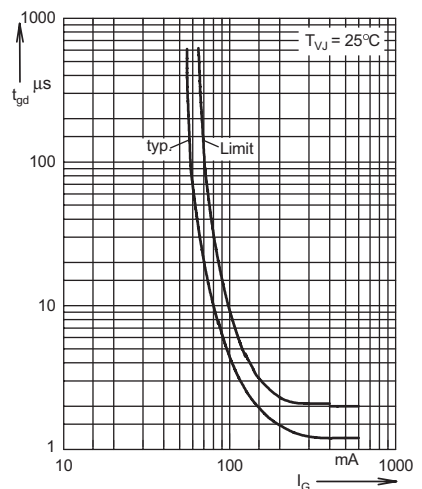


Fig. 6 Gate trigger delay time

# STT27GKxx

## Thyristor-Thyristor Modules

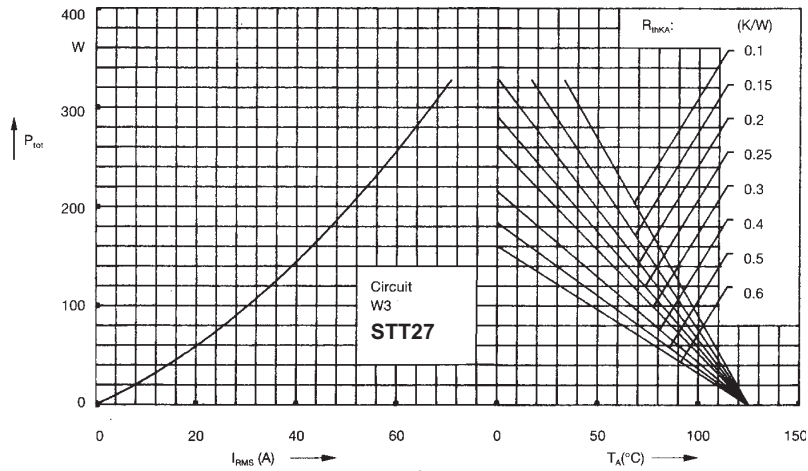


Fig. 7 Three phase AC-controller: Power dissipation versus RMS output current and ambient temperature

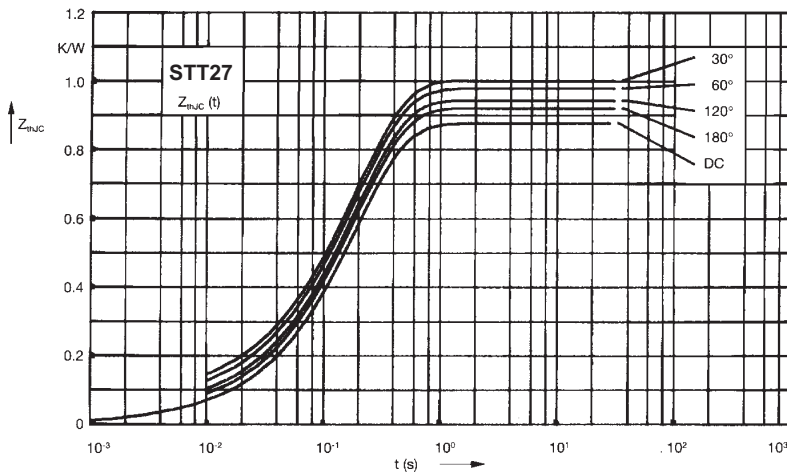


Fig. 8 Transient thermal impedance junction to case (per thyristor or diode)

$R_{thJC}$  for various conduction angles d:

d	$R_{thJC}$ (K/W)
DC	0.88
180°	0.92
120°	0.95
60°	0.98
30°	1.01

Constants for  $Z_{thJC}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.019	0.0031
2	0.029	0.0216
3	0.832	0.191

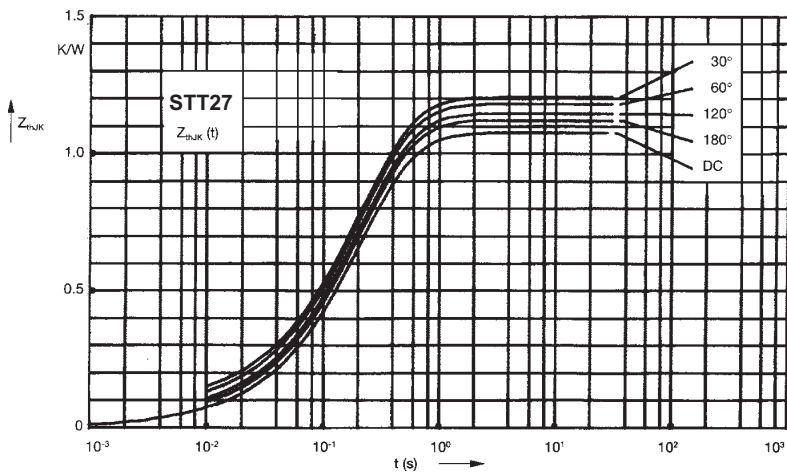


Fig. 9 Transient thermal impedance junction to heatsink (per thyristor or diode)

$R_{thJK}$  for various conduction angles d:

d	$R_{thJK}$ (K/W)
DC	1.08
180°	1.12
120°	1.15
60°	1.18
30°	1.21

Constants for  $Z_{thJK}$  calculation:

i	$R_{thi}$ (K/W)	$t_i$ (s)
1	0.019	0.0031
2	0.029	0.0216
3	0.832	0.191
4	0.2	0.45